Product Change Notification

Change Notification #:	**114876 - 01**
Change Title:	**Intel® Compute Module HNS2600KPR and Intel® Compute Module HNS2600TPFR PCN 114876-01, Product Material, Product Design, Replacement of components listed under RoHS exemption 7c-I, Change Node Tray Assembly** **Reason for revision:** ROHS cut-in date for the HNS2600TPFR changed
Date of Publication:	**September 8, 2016**

Key Characteristics of the Change:

Product Material, Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	September 16, 2016

Reason for Revision: ROHS cut-in date for the Intel® Compute Module HNS2600TPFR has changed. A tray assembly change to support NVDIMM supercaps and, and IOM blank filler change to support the M.2 carrier has been promoted.

Description of Changes to the Customer:

1. Intel is replacing components containing substances listed under EU RoHS exemption 7c-I with exemption-free components for the Intel® Compute Module HNS2600KPR. All new components are identical in form factor and function to the replaced ones. The following Products Affected table defines the associated TA and PBA changes.
2. Intel is implementing the following change on the Intel® Compute Module HNS2600TPFR node tray assembly to support NVDIMM supercaps. The following Products Affected table defines the associated TA changes.
3. Intel is implementing the following change on the Intel® Compute Module HNS2600TPFR node IOM blank filler to support the M.2 carrier. The following Products Affected table defines the associated TA changes.

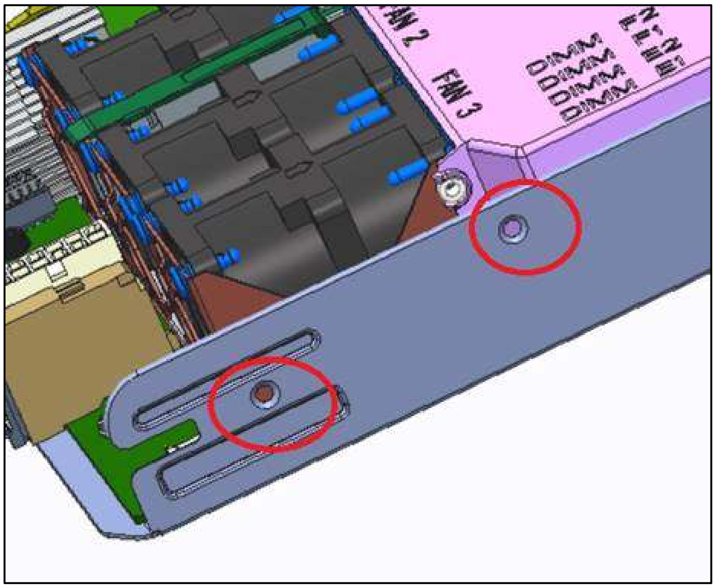

Figure 1. Post-Change Tray Assembly

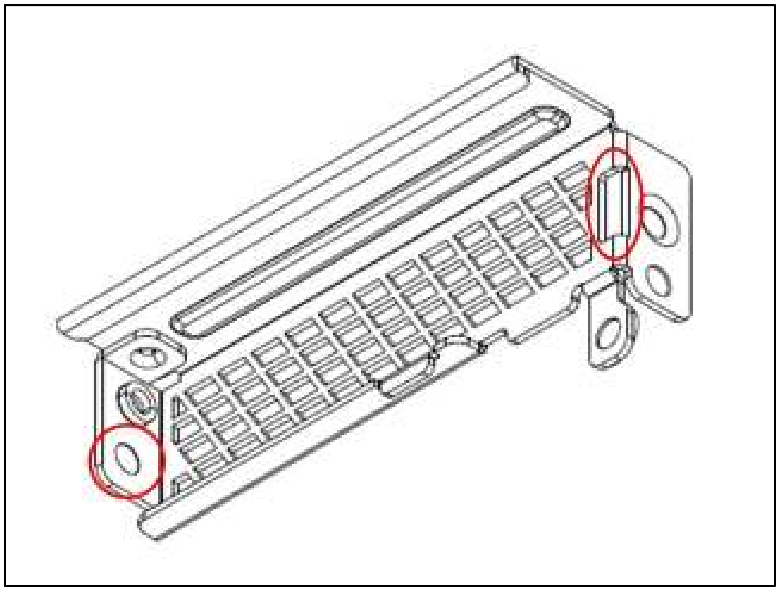

Figure 2. Post-Change IOM Blank Filler

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
HNS2600KPR	943787	H94936-003	H13888-361	H94936-004	H13888-371
HNS2600TPFR	943949	H94939-002	H14263-261	H94939-003	H14263-261

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
September 1, 2016	00	Originally Published PCN
September 8, 2016	01	ROHS cut-in date for the Intel® Compute Module HNS2600TPFR has changed. A tray assembly change to support NVDIMM supercaps and, and IOM blank filler change to support the M.2 carrier has been promoted.

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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